

ABSTRACT

~~In order to~~To reduce the capacitance of an electronic module ~~comprising~~having an active component (1) bonded to a base (2), thereby enabling its cutoff frequency to be raised, the method ~~consists in providing~~provides a plurality of contact pads (P1, P'1, P2, P3, P'3) and a plurality of contact zones (Z1, Z'1, Z2, Z3, Z'3) on the component and on the base respectively. First structures (P1, P'1, Z1, Z'1) are adapted to be bonded together by melting solder. Second structures (P2, Z2) of small surface area are designed to be bonded together by thermal compression delivered by the mutual force of attraction that results between the component and the base due to the solder melting. The invention is particularly applicable to making optoelectronic components used in high data rate optical transmission systems.